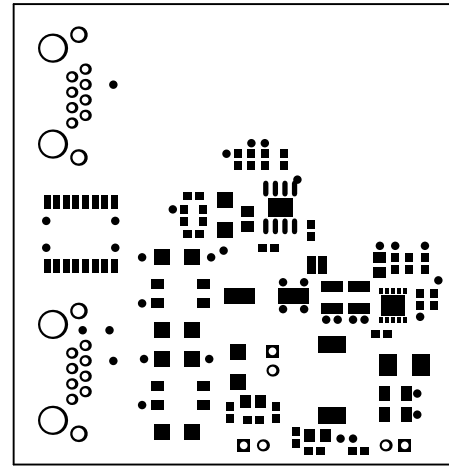
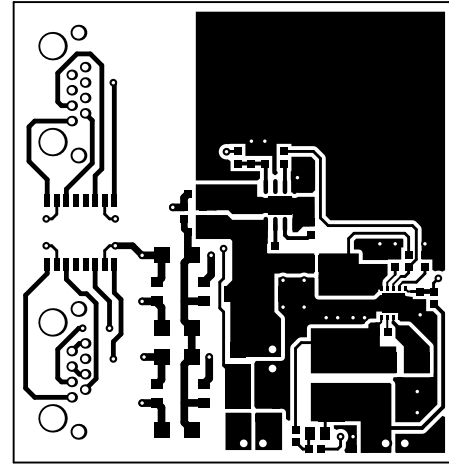


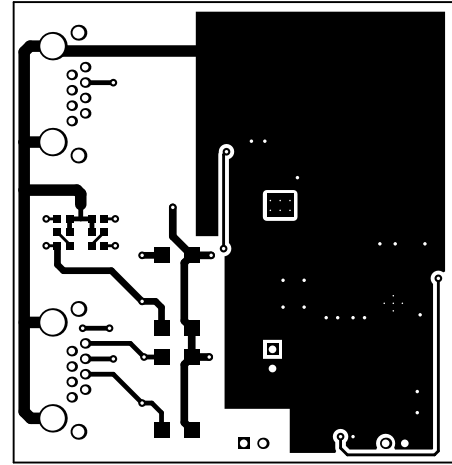
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10812	REV: A	SVN REV: Not In VersionControl
LAYER NAME = Top Overlay			
PLOT NAME = Top Overlay	GENERATED : 11/3/2017 4:01:03 PM	TEXAS INSTRUMENTS	



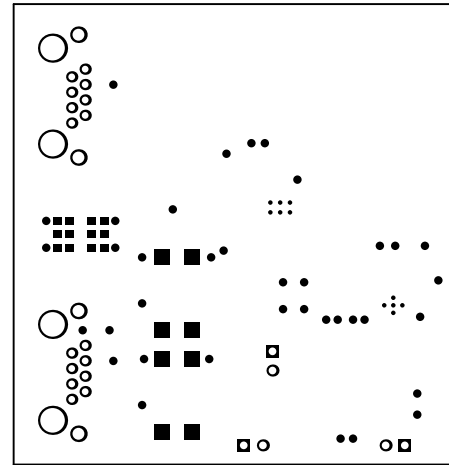
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10812	REV: A	SVN REV: Not In VersionControl
LAYER NAME = Top Solder			
PLOT NAME = Top Solder Mask	GENERATED : 11/3/2017 4:01:03 PM	TEXAS INSTRUMENTS	



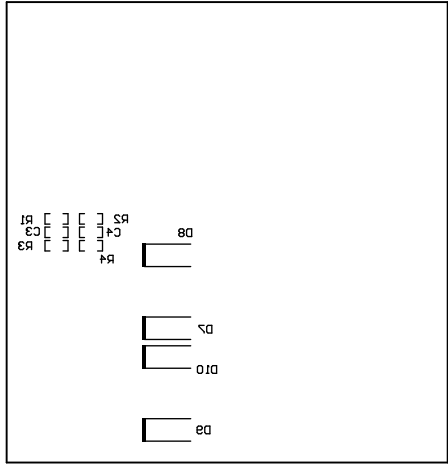
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10812	REV: A	SVN REV: Not In VersionControl
LAYER NAME = Top Layer			
PLOT NAME = Top Layer	GENERATED : 11/3/2017 4:01:04 PM	TEXAS INSTRUMENTS	



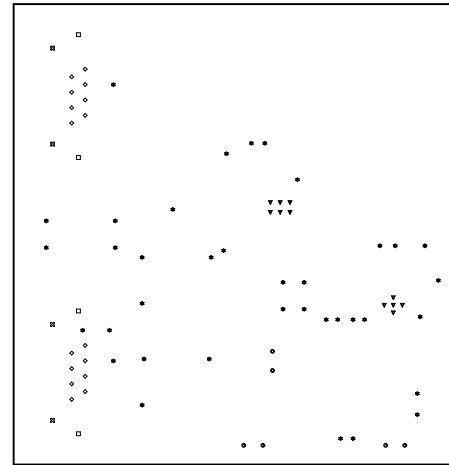
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10812	REV: A	SVN REV: Not In VersionControl
LAYER NAME = Bottom Layer			
PLOT NAME = Bottom Layer	GENERATED : 11/3/2017 4:01:05 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10812	REV: A	SVN REV: Not In VersionControl
LAYER NAME = Bottom Solder			
PLOT NAME = Bottom Solder Mask	GENERATED : 11/3/2017 4:01:05 PM	TEXAS INSTRUMENTS	

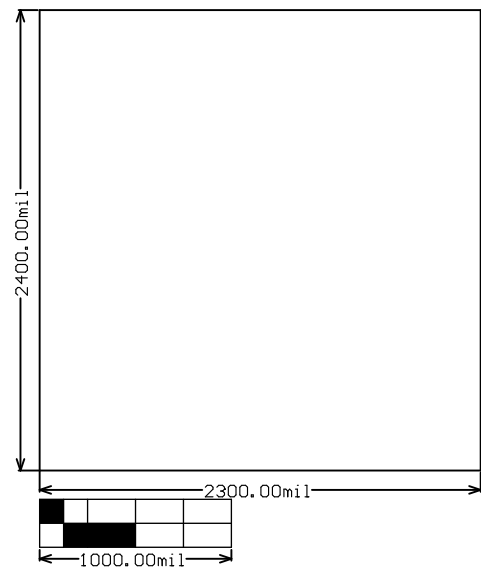


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10812	REV: A	SVN REV: Not In VersionControl
LAYER NAME = Bottom Overlay			
PLOT NAME = Bottom Overlay	GENERATED : 11/3/2017 4:01:06 PM	TEXAS INSTRUMENTS	



Symbol	Quantity	Finished Hole Size	Plated	Hole Type
▽	11	7.87mil (0.200mm)	PTH	Round
★	37	18.00mil (0.457mm)	PTH	Round
◇	16	35.04mil (0.890mm)	PTH	Round
●	6	40.00mil (1.016mm)	PTH	Round
□	4	61.81mil (1.570mm)	PTH	Round
⊗	4	128.00mil (3.251mm)	PTH	Round
78 Total				

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10812	REV: A	SVN REV: Not In VersionControl
LAYER NAME = Drill Drawing			
PLOT NAME = Drill Drawing	GENERATED : 11/3/2017	4:01:07 PM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10812	REV: A	SVN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions			
PLOT NAME = Board Dimensions	GENERATED : 11/3/2017 4:01:08 PM	TEXAS INSTRUMENTS	



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